

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Zigmund R. Camacho</td> <td>03/03/2008</td> </tr> <tr> <td>Henry D. Bathan</td> <td>03/04/2008</td> </tr> <tr> <td>Lionel Chien Hui Tay</td> <td>03/04/2008</td> </tr> <tr> <td>Arnel S. Trasporto</td> <td>03/04/2008</td> </tr> </tbody> </table>		Name	Execution Date	Zigmund R. Camacho	03/03/2008	Henry D. Bathan	03/04/2008	Lionel Chien Hui Tay	03/04/2008	Arnel S. Trasporto	03/04/2008
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Henry D. Bathan	03/04/2008										
Lionel Chien Hui Tay	03/04/2008										
Arnel S. Trasporto	03/04/2008										
RECEIVING PARTY DATA											
Name:	STATS ChipPAC, Ltd.										
Street Address:	10 Ang Mo Kio Street 65										
Internal Address:	#05-17/20 Techpoint										
City:	Singapore										
State/Country:	SINGAPORE										
Postal Code:	569059										
PROPERTY NUMBERS Total: 1											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12044688</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12044688						
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CORRESPONDENCE DATA											
Fax Number:	(602)229-5690										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
Phone:	602-229-5290										
Email:	moneill@quarles.com										
Correspondent Name:	Robert D. Atkins										
Address Line 1:	QUARLES & BRADY LLP										
Address Line 2:	TWO NORTH CENTRAL AVENUE										
Address Line 4:	PHOENIX, ARIZONA 85004-2391										
ATTORNEY DOCKET NUMBER:	125155.00087										
NAME OF SUBMITTER:	Robert D. Atkins										

CH \$40.00 12044688

Total Attachments: 4

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ASSIGNMENT AND AGREEMENT

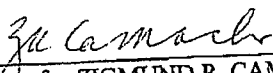
For good and valuable consideration, the receipt of which is hereby acknowledged, I, ZIGMUND R. CAMACHO of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled OPTICAL SEMICONDUCTOR DEVICE HAVING PRE-MOLDED LEADFRAME WITH WINDOW AND METHOD THEREFOR, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00087, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.



Signature for ZIGMUND R. CAMACHO

Witnessed on this date: March 3, 2008

Signature of Witness: 

Printed Name of Witness: JOSE ALVIN CAPARAS

Address of Witness: BLK 313 #10-474

SEMBAWANG DRIVE (S) 70313

QBACTIVE\6126983.1

ASSIGNMENT AND AGREEMENT

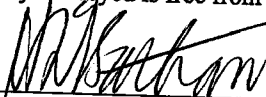
For good and valuable consideration, the receipt of which is hereby acknowledged, I, HENRY D. BATHAN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled OPTICAL SEMICONDUCTOR DEVICE HAVING PRE-MOLDED LEADFRAME WITH WINDOW AND METHOD THEREFOR, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00087, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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Signature for HENRY D. BATHAN

Witnessed on this date:

March 4, 2008

Signature of Witness:



Printed Name of Witness:

CHOW SENG GUAN

Address of Witness:

BLK 131, YISHUN ST. 11
#07-243, SINGAPORE 760131

QBACTIVE\6080388.1

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, LIONEL CHIEN HUI TAY of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled OPTICAL SEMICONDUCTOR DEVICE HAVING PRE-MOLDED LEADFRAME WITH WINDOW AND METHOD THEREFOR, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00087, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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Signature for LIONEL CHIEN HUI TAY

Witnessed on this date: March 4, 2008

Signature of Witness: 

Printed Name of Witness: CHOW SENG GUAN

Address of Witness: BLK 131, YISHUN ST. 11

07-243, SINGAPORE 760131

QBACTIVE\6080381.1

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, ARNEL S. TRASPORTO of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled OPTICAL SEMICONDUCTOR DEVICE HAVING PRE-MOLDED LEADFRAME WITH WINDOW AND METHOD THEREFOR, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00087, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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Signature for ARNEL S. TRASPORTO

Witnessed on this date: March 4, 2008

Signature of Witness: 

Printed Name of Witness: CHOW SENG GUAN

Address of Witness: BLK 131, YISHUN ST. 11
#07-243, SINGAPORE 760131

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